

ABSTRACT

A semiconductor package having conductive bumps on a chip and a fabrication method thereof are provided. A plurality of the conductive bumps are deposited respectively on bond pads of the chip. An encapsulation body encapsulates the chip and conductive bumps while exposing ends of the conductive bumps. A plurality of conductive traces are formed on the encapsulation body and electrically connected to the exposed ends of the conductive bumps. A solder mask layer is applied over the conductive traces and formed with openings for exposing predetermined portions of the conductive traces. The exposed portions of the conductive traces are connected to a plurality of solder balls respectively. The conductive bumps on the bond pads of the chip allow easy positional recognition of the bond pads, making the conductive traces well electrically connected to the bond pads through the conductive bumps and assuring the quality and reliability of the semiconductor package.

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